

KMPR 1015 – run sheet

Kayaku Advanced Materials

nanyte.com/photoresists/kmpr-1015 · last updated 2026-09-12

Thickness: 12.5–40 μm

Softbake: 100 °C (95–105 °C) · hotplate

Exposure dose – dose by film thickness

Film thickness	Dose
12–20 μm	355–485 mJ/cm^2
21–30 μm	500–645 mJ/cm^2
31–55 μm	665–1055 mJ/cm^2

Post-exposure bake: 100 °C (95–105 °C) · hotplate

Develop: Developer 2.38 % TMAH (0.26 N) aqueous alkaline developer; SU-8 developer (solvent) may be used instead · Rinse After TMAH, spray rinse with de-ionized water for 20 s and blow dry with filtered air or nitrogen. After SU-8 developer, spray with fresh developer for about 10 s, then isopropyl alcohol for another 10 s, then blow dry – a white film during the IPA rinse means the film is under-developed and needs more developer. · Method immersion, spray or spray-puddle